

### ● General Description

The AGM056N10C combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ .

This device is ideal for load switch and battery protection applications.

### ● Features

- Advance high cell density Trench technology
- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

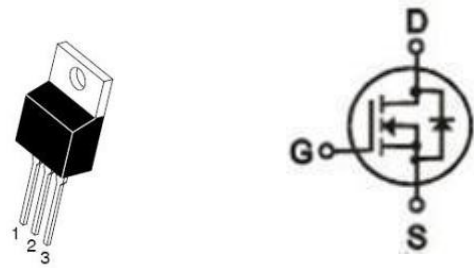
### ● Application

- MB/VGA Vcore
- SMPS 2<sup>nd</sup> Synchronous Rectifier
- POL application
- BLDC Motor driver

### Product Summary

| BVDSS | RDSON | ID   |
|-------|-------|------|
| 100V  | 5.4mΩ | 140A |

### TO-220 Pin Configuration



### Package Marking and Ordering Information

| Device Marking | Device     | Device Package | Reel Size | Tape width | Quantity |
|----------------|------------|----------------|-----------|------------|----------|
| AGM056N10C     | AGM056N10C | TO-220         | ----      | ----       | 1000     |

**Table 1. Absolute Maximum Ratings (TA=25°C)**

| Symbol      | Parameter  | Value      | Unit |
|-------------|--|------------|------|
| VDS         | Drain-Source Voltage (VGS=0V)                            | 100        | V    |
| VGS         | Gate-Source Voltage (VDS=0V)                             | ±20        | V    |
| ID          | Drain Current-Continuous(Tc=25°C) <b>(Note 1)</b>        | 140        | A    |
|             | Drain Current-Continuous(Tc=100°C)                       | 95         | A    |
| IDM (pluse) | Drain Current-Continuous@ Current-Pulsed <b>(Note 2)</b> | 390        | A    |
| PD          | Maximum Power Dissipation(Tc=25°C)                       | 227        | w    |
|             | MaximumPowerDissipation(Tc=100 °C)                       | 91         | w    |
| EAS         | Avalanche energy <b>(Note 3)</b>                         | 400        | mJ   |
| TJ,TSTG     | Operating Junction and Storage Temperature Range         | -55 To 150 | °C   |

**Table 2. Thermal Characteristic**

| Symbol | Parameter   | Typ | Max  | Unit |
|--------|---|-----|------|------|
| RθJA   | Thermal Resistance Junction-ambient (Steady State) <sup>1</sup> | --- | 65   | °C/W |
| RθJC   | Thermal Resistance Junction-Case <sup>1</sup>                   | --- | 0.55 | °C/W |

**Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)**

| Symbol                                    | Parameter                        | Conditions                          | Min | Typ  | Max  | Unit |
|---|----------------------------------|-------------------------------------|-----|------|------|------|
| <b>On/Off States</b>                      |                                  |                                     |     |      |      |      |
| BVDSS                                     | Drain-Source Breakdown Voltage   | VGS=0V ID=250μA                     | 100 | --   | --   | V    |
| IDSS                                      | Zero Gate Voltage Drain Current  | VDS=100V,VGS=0V                     | --  | --   | 1    | μA   |
| IGSS                                      | Gate-Body Leakage Current        | VGS=±20V,VDS=0V                     | --  | --   | ±100 | nA   |
| VGS(th)                                   | Gate Threshold Voltage           | VDS=VGS,ID=250μA                    | 2   | 2.8  | 4    | V    |
| gFS                                       | Forward Transconductance         | VDS=5V,ID=20A                       | --  | 75   | --   | S    |
| RDS(on)                                   | Drain-Source On-State Resistance | VGS=10V, ID=20A                     | --  | 5.4  | 6.8  | mΩ   |
|   |                                  | VGS=4.5V, ID=7A                     | --  | --   | --   | mΩ   |
| <b>Dynamic Characteristics</b>            |                                  |                                     |     |      |      |      |
| Ciss                                      | Input Capacitance                | VDS=50V,VGS=0V,<br>F=1MHZ           | --  | 3650 | --   | pF   |
| Coss                                      | Output Capacitance               |                                     | --  | 290  | --   | pF   |
| Crss                                      | Reverse Transfer Capacitance     |                                     | --  | 88   | --   | pF   |
| Rg  | Gate resistance                  | VGS=0V,<br>VDS=0V,f=1.0MHz          | --  | 1.6  | --   | Ω    |
| <b>Switching Times</b>                    |                                  |                                     |     |      |      |      |
| td(on)                                    | Turn-on Delay Time               | VGS=10V,VDS=50V,<br>ID=20A,RGEN=10Ω | --  | 17   | --   | nS   |
| tr  | Turn-on Rise Time                |                                     | --  | 40   | --   | nS   |
| td(off)                                   | Turn-Off Delay Time              |                                     | --  | 57   | --   | nS   |
| tf  | Turn-Off Fall Time               |                                     | --  | 37   | --   | nS   |
| Qg  | Total Gate Charge                | VGS=10V, VDS=50V,<br>ID=20A         | --  | 56   | --   | nC   |
| Qgs                                       | Gate-Source Charge               |                                     | --  | 14   | --   | nC   |
| Qgd                                       | Gate-Drain Charge                |                                     | --  | 18   | --   | nC   |
| <b>Source-Drain Diode Characteristics</b> |                                  |                                     |     |      |      |      |
| ISD                                       | Source-Drain Current(Body Diode) |                                     | --  | --   | 140  | A    |
| VSD                                       | Forward on Voltage               | VGS=0V,IS=20A                       | --  | 0.9  | 1.2  | V    |
| trr                                       | Reverse Recovery Time            | IF=20A , dI/dt=500A/μs ,<br>TJ=25°C | --  | 50   | --   | ns   |
| Qrr                                       | Reverse Recovery Charge          |                                     | --  | 255  | --   | nc   |

Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25°C

Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

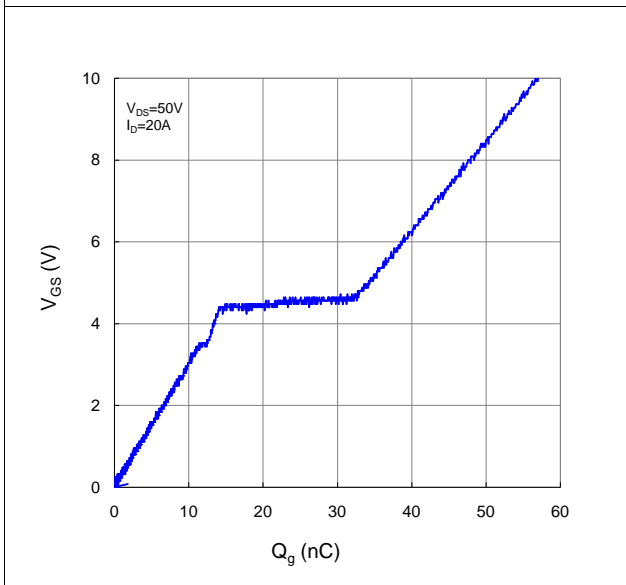


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

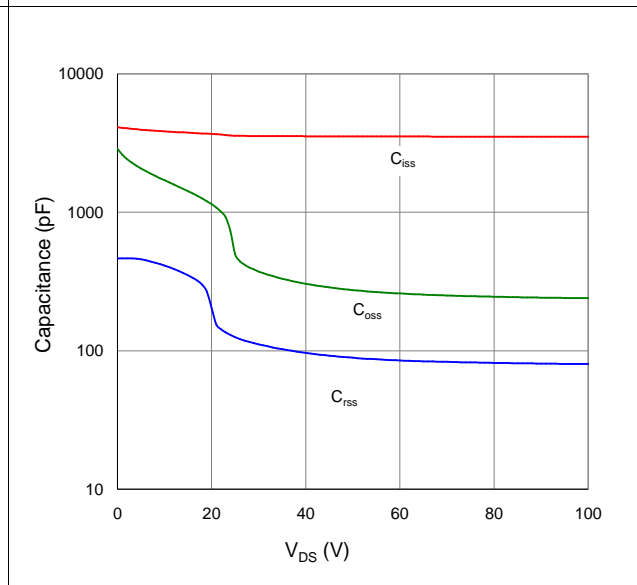


Figure 9. Maximum Safe Operating Area

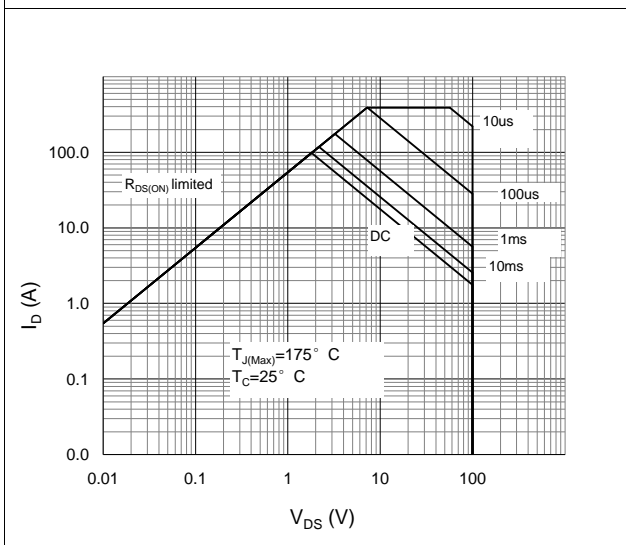


Figure 10. Maximun Drain Current vs. Case Temperature

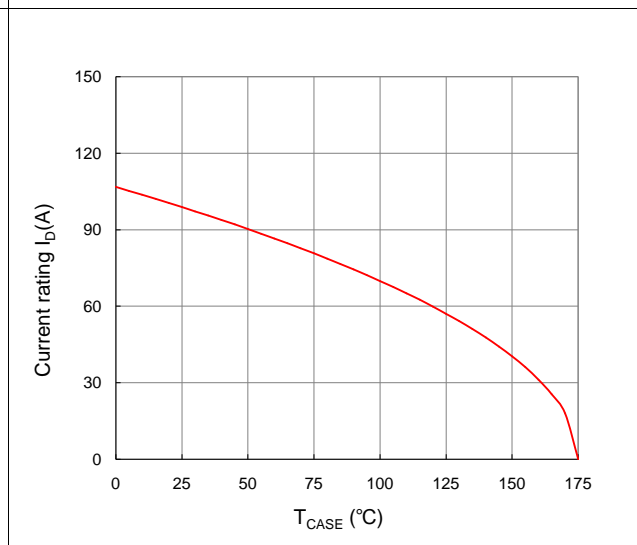


Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case

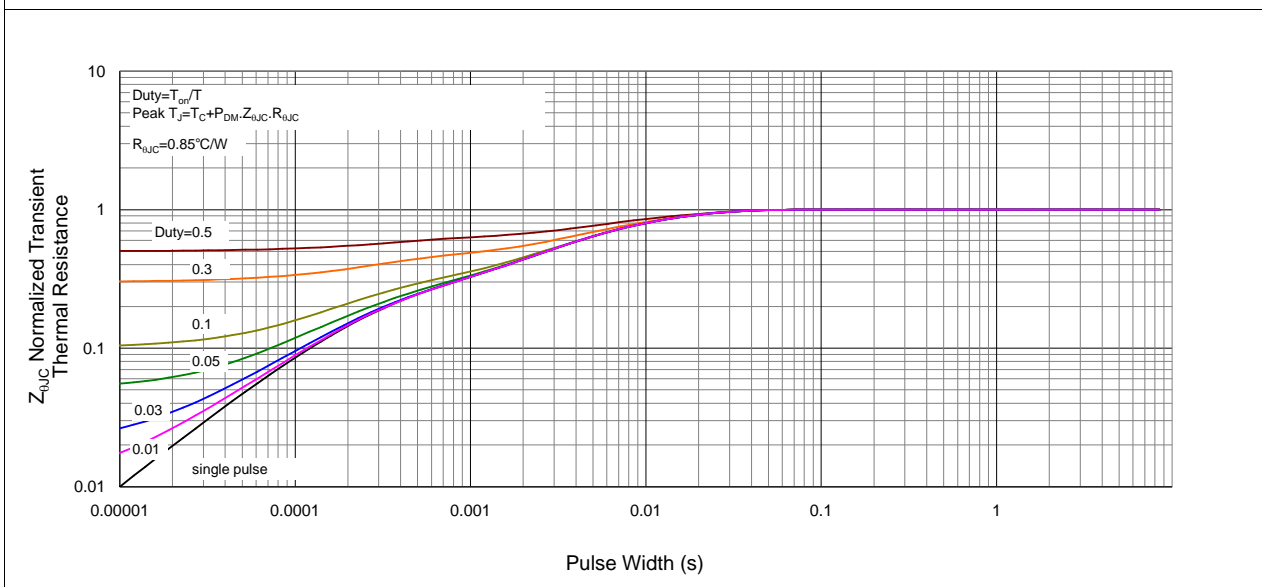


Fig 1. Typical Output Characteristics

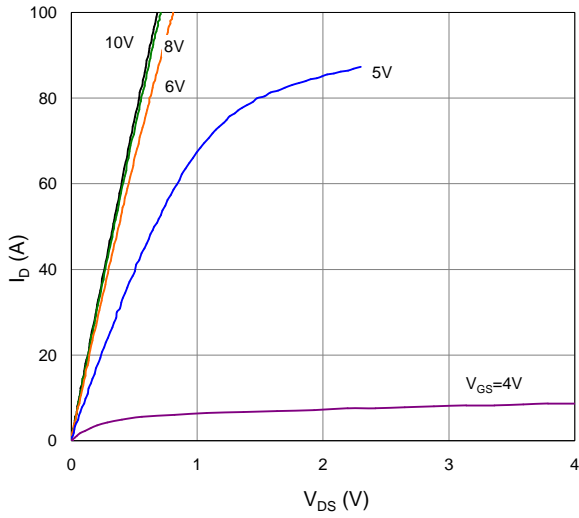


Figure 2. On-Resistance vs. Gate-Source Voltage

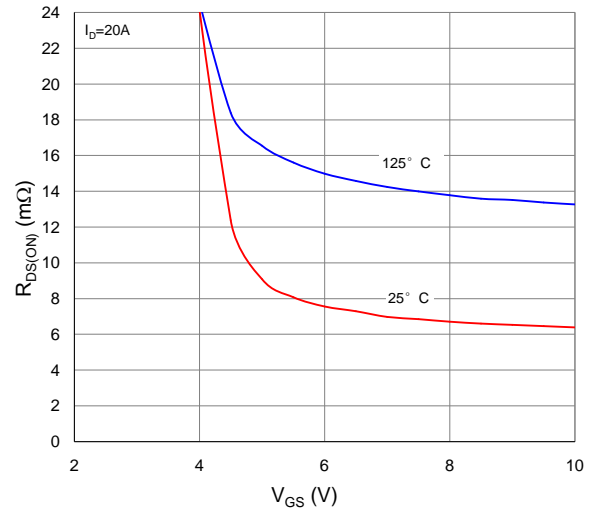


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

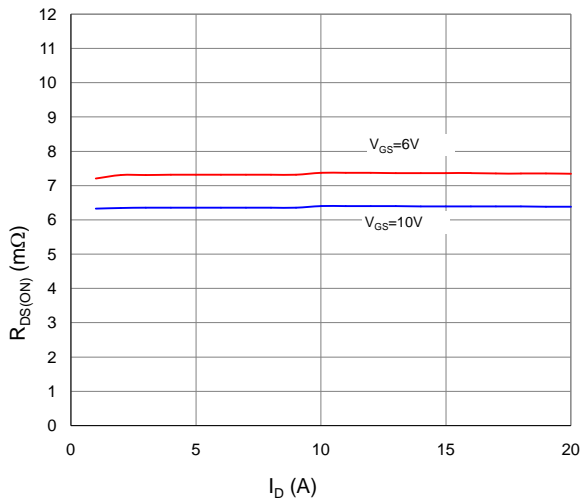


Figure 4. Normalized On-Resistance vs. Junction Temperature

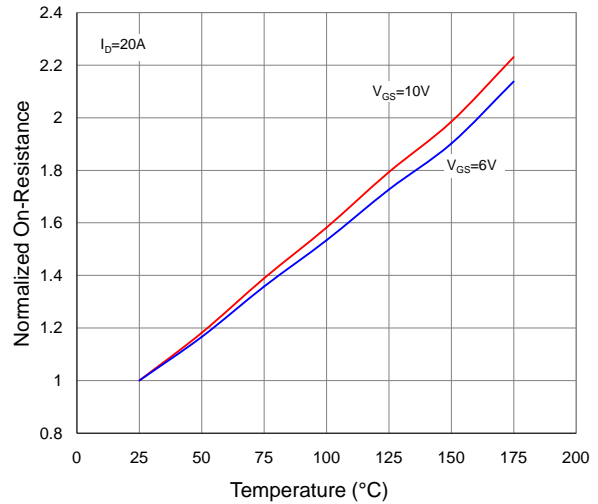


Figure 5. Typical Transfer Characteristics

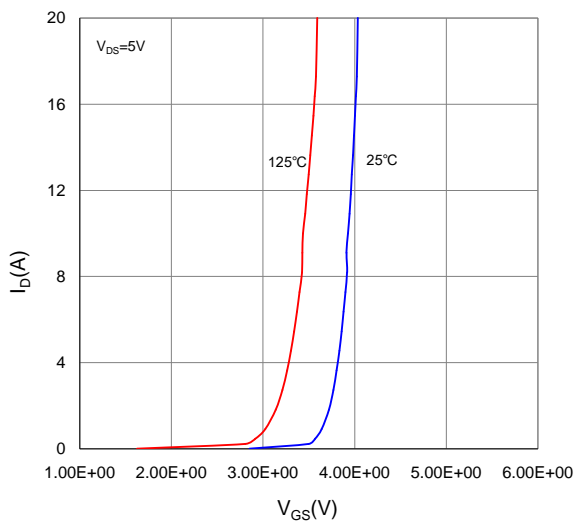
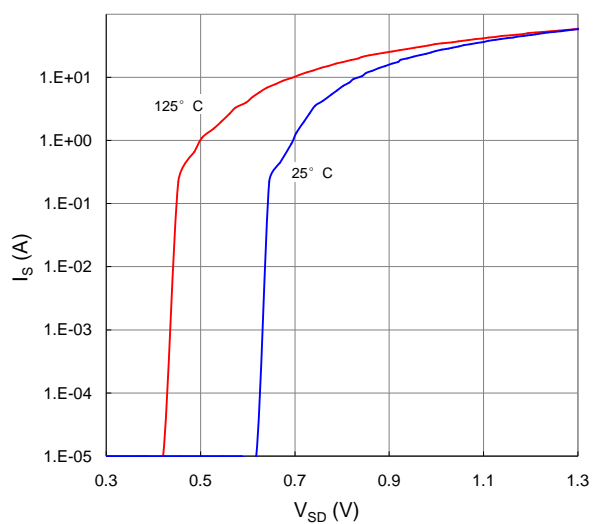
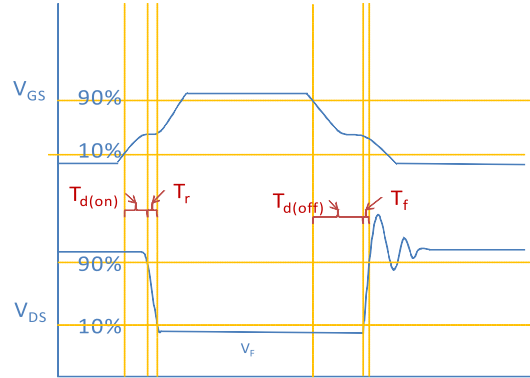
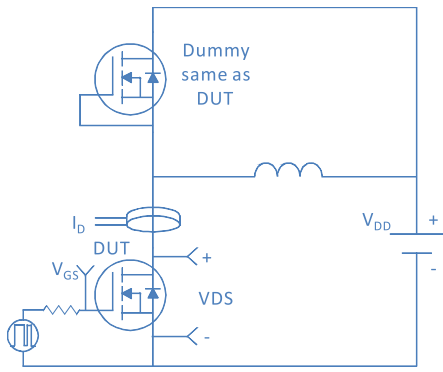
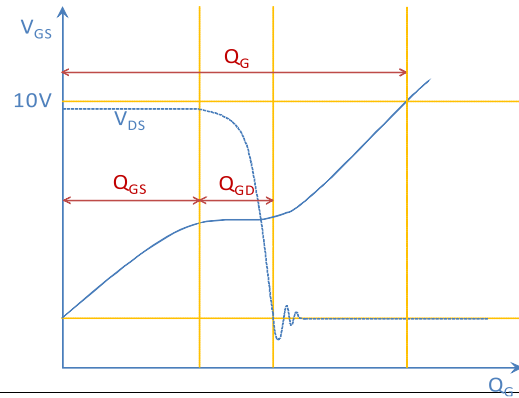
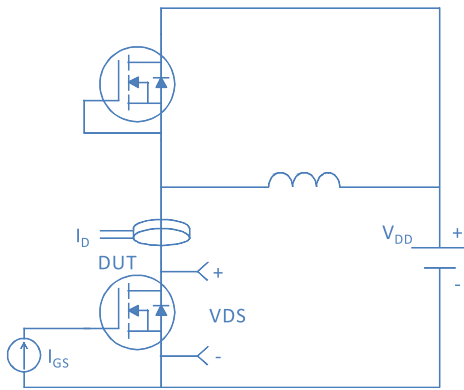
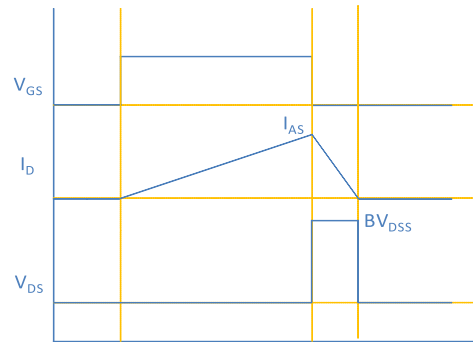
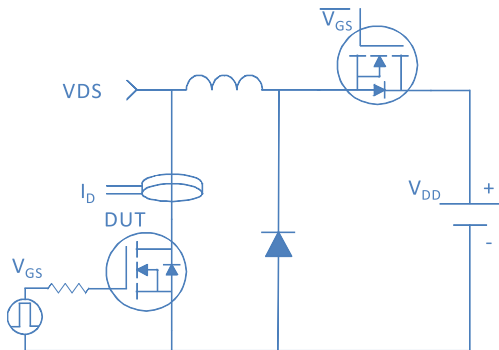
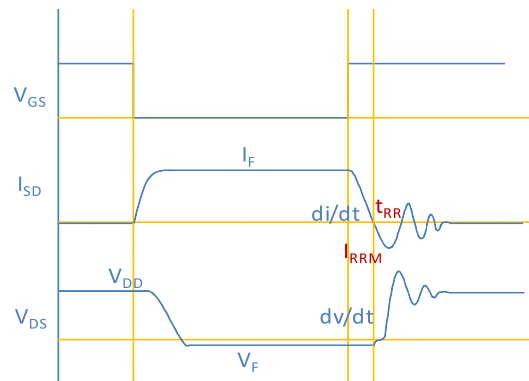
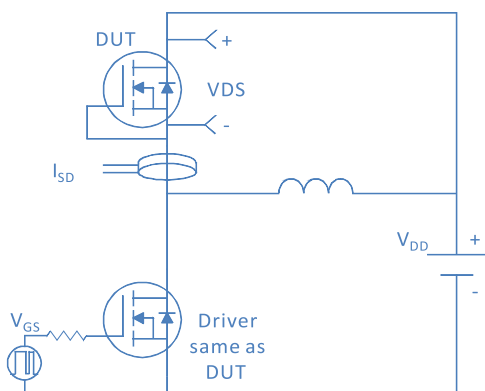
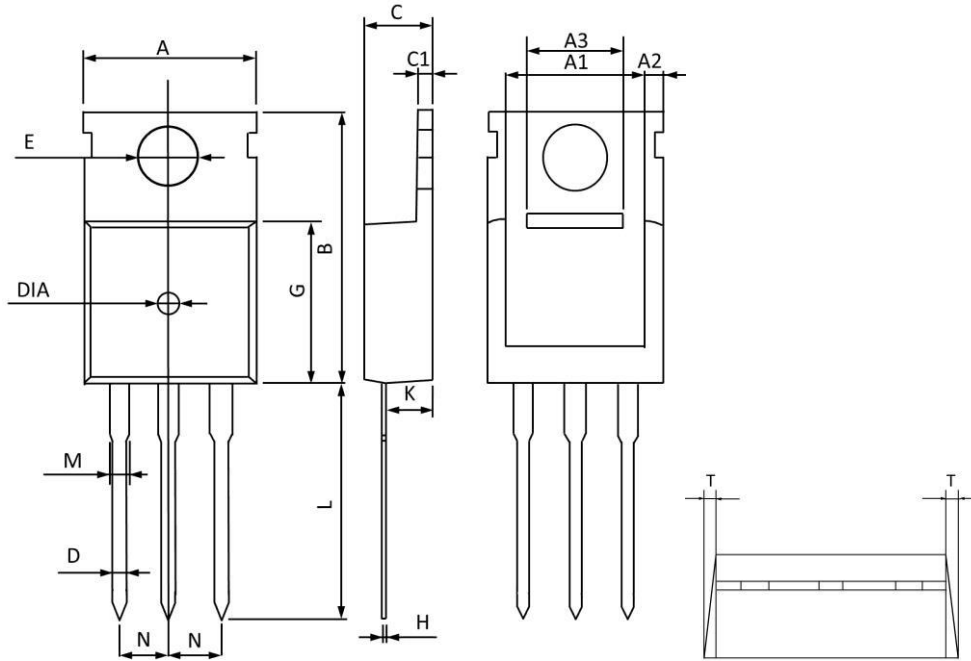


Figure 6. Typical Source-Drain Diode Forward Voltage



**Inductive switching Test**

**Gate Charge Test**

**Uclamped Inductive Switching (UIS) Test**

**Diode Recovery Test**


## TO220 PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters |              | Dimensions In Inches |                |
|--------|---------------------------|--------------|----------------------|----------------|
|        | MAX                       | MIN          | MAX                  | MIN            |
| A      | 10.300                    | 9.700        | 0.406                | 0.382          |
| A1     | 8.840                     | 8.440        | 0.348                | 0.332          |
| A2     | 1.250                     | 1.050        | 0.049                | 0.041          |
| A3     | 5.300                     | 5.100        | 0.209                | 0.201          |
| B      | 16.200                    | 15.400       | 0.638                | 0.606          |
| C      | 4.680                     | 4.280        | 0.184                | 0.169          |
| C1     | 1.500                     | 1.100        | 0.059                | 0.043          |
| D      | 1.000                     | 0.600        | 0.039                | 0.024          |
| E      | 3.800                     | 3.400        | 0.150                | 0.134          |
| G      | 9.300                     | 8.700        | 0.366                | 0.343          |
| H      | 0.600                     | 0.400        | 0.024                | 0.016          |
| K      | 2.700                     | 2.100        | 0.106                | 0.083          |
| L      | 13.600                    | 12.800       | 0.535                | 0.504          |
| M      | 1.500                     | 1.100        | 0.059                | 0.043          |
| N      | 2.590                     | 2.490        | 0.102                | 0.098          |
| T      | W0.35                     |              | W0.014               |                |
| DIA    | Φ1.5 TYP.                 | deep0.2 TYP. | Φ0.059 TYP.          | deep0.008 TYP. |


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